T3 / DS3 / E3 / STS-1 TRANSFORMERS

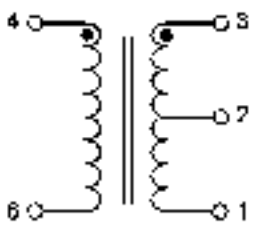
- **DEVELOPED FOR USE IN T3, DS3, E3, AND STS-1 INTERFACES**
- **RETURN LOSS MEETS REQUIREMENTS OF G.703**
- **FAST RISE TIMES**
- **THROUGH-HOLE AND SURFACE MOUNT PACKAGES AVAILABLE**
- **1500 Vrms ISOLATION AND 3000 Vrms REINFORCED INSULATION PER BABT EN41003/EN60950 AND UL 1950 AVAILABLE**
- **SINGLE, DUALS, CUSTOMS AVAILABLE**

ELECTRICAL SPECIFICATIONS @ 25° C

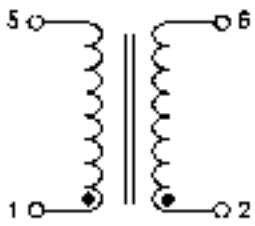
Part Number	Turns Ratio (± 2%)	OCL Primary (µH MIN)	L_L (µH MAX)	Bandwidth 75 Ω System (MHz TYP)	Isolation Voltage (Vms MIN)	Package/ Schematic	Primary Pins
XF04061-2B	1:1	40	.12	—	1500	XF-2B / C	2-6
XF03561-2B	1:2CT	35	.12	—	1500	XF-2B / E	2-6
XF05061-2B	1:4CT	150	.30	—	1500	XF-2B / E	2-6
XF0506-20	1:1.73CT	50	.10	.060 - 300	1500	XF-20 / A	4-6
XF04061-20	1:1	40	.10	.200 - 340	1500	XF-20 / B	4-6
XF04061-2S	1:1	40	.10	.200 - 340	1500	XF-2S / B	4-6
XF01962-20	1:2CT	19	.06	.250 - 500	1500	XF-2S / A	4-6
XF01962-2S	1:2CT	19	.06	.250 - 500	1500	XF-20 / A	4-6
XF0406TM	1:1	40	.10	—	3000	XF-TM / D	1-5
XF0196TM	1:2CT	19	.06	—	3000	XF-TM / C	1-5
XF04061-2SA	1:1	40	.20	—	3000	XF-2S / B	4-6
XF01962-20A	1:2CT	19	.20	—	3000	XF-2S / A	4-6

SCHEMATICS:

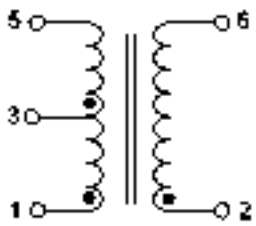
A



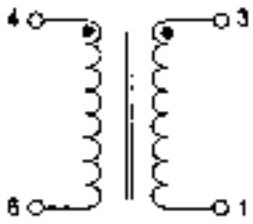
C



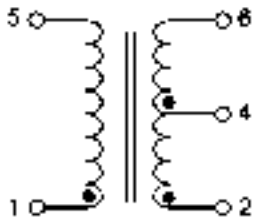
E



B



D

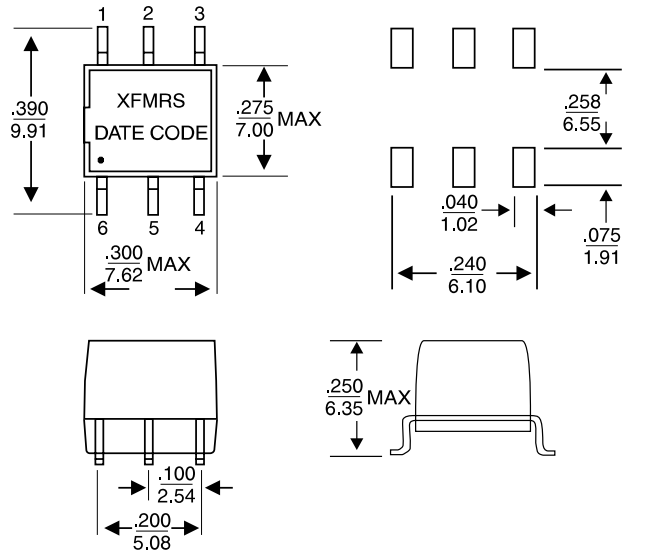


T3 / DS3 / E3 / STS-1
TRANSFORMERS

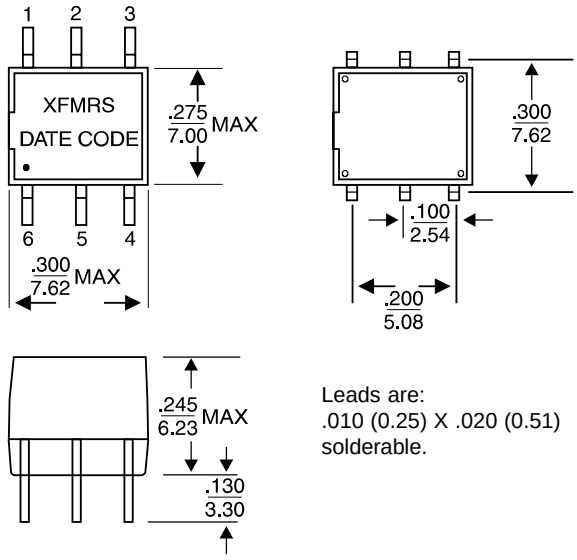
Dimensions: (Inches / mm)

XF-2S

SUGGESTED PAD LAYOUT

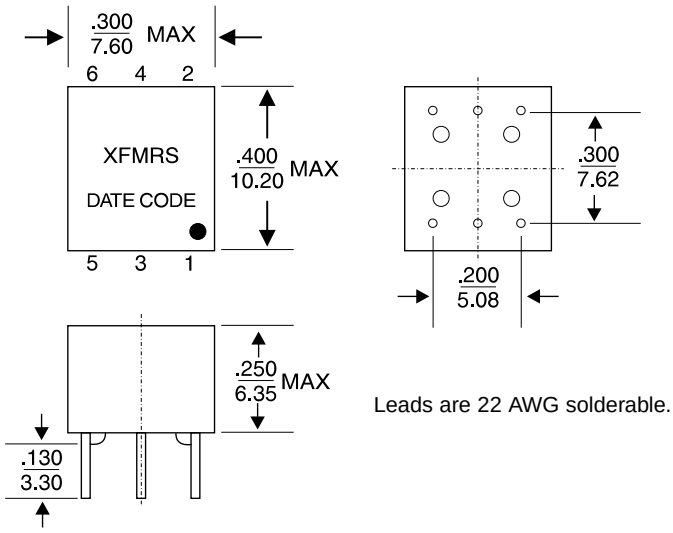


XF-20



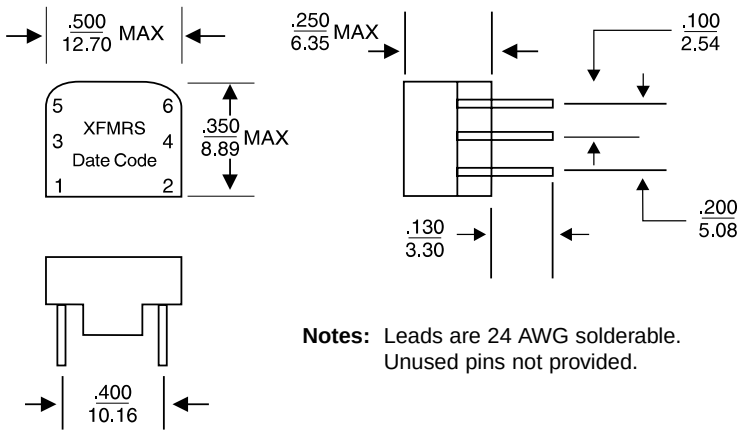
Leads are:
.010 (0.25) X .020 (0.51)
solderable.

XF-2B



Leads are 22 AWG solderable.

XF-TM



Notes: Leads are 24 AWG solderable.
Unused pins not provided.